



LED420-01

Rev 2.0, 28.11.2018

- Violet LED
- 420 nm, 26 mW
- Chip: InGaN, 350 x 300 µm
- 5 mm Clear Molding, UV Epoxy Resin
- Viewing Angle: 14°



Description

LED420-01 contains one InGaN LED chip die mounted on a lead frame hermetically sealed with a clear epoxy lens.

On forward bias, it emits a power radiation of typical **26 mW** at a peak wavelength at **420 nm**.

Maximum Ratings ($T_{CASE}=25^\circ\text{C}$)

Parameter	Symbol	Min.	Values	Max.	Unit
Power Dissipation	P_D			220	mW
Forward Current	I_F			50	mA
Pulse Forward Current *1	I_{FP}			100	mA
Reverse Voltage	V_F			5	V
Thermal Resistance	R_{THJA}			230	K/W
Junction Temperature	T_J			120	°C
Operating Temperature	T_{CASE}	- 20		+ 100	°C
Storage Temperature	T_{STG}	- 20		+ 100	°C
Lead Solder Temperature *2	T_{SLD}			+ 265	°C

*1 duty=1%, pulse width = 10 µs

*2 must be completed within 3 seconds

Electro-Optical Characteristics ($T_{CASE}=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Min.	Values	Typ.	Max.	Unit
Peak Wavelength	λ_P	$I_F=20\text{mA}$	410			430	nm
Dominant Wavelength	λ_D	$I_F=20\text{mA}$			432		
Half Width	$\Delta\lambda$	$I_F=20\text{mA}$			16		nm
Forward Voltage	V_F	$I_F=20\text{mA}$			3.2		
	V_{FP}	$I_{FP}=100\text{mA}$			4.2		V
Radiated Power *1	P_O	$I_F=20\text{mA}$			26		
		$I_{FP}=100\text{mA}$			100		mW
Radiant Intensity *2	I_E	$I_F=20\text{mA}$			210		
		$I_{FP}=100\text{mA}$			800		mW/sr
Luminous Flux	Φ_V	$I_F=20\text{mA}$			180		mlm
Viewing Angle	φ	$I_F=20\text{mA}$			14		deg.
Rise Time	t_R	$I_F=20\text{mA}$			15		ns
Fall Time	t_F	$I_F=20\text{mA}$			15		ns

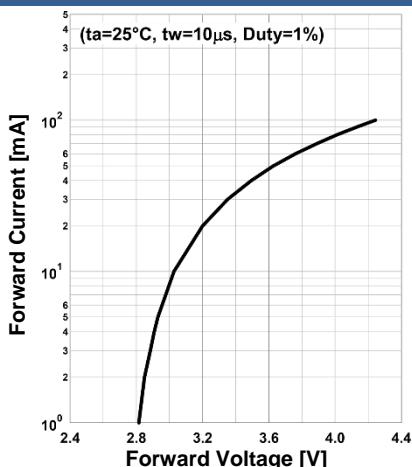
*1 measured by S3584-08

*2 measured by CIE127-2007 Condition B

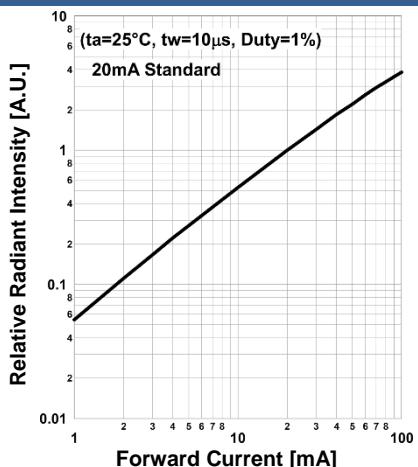


Typical Performance Curves

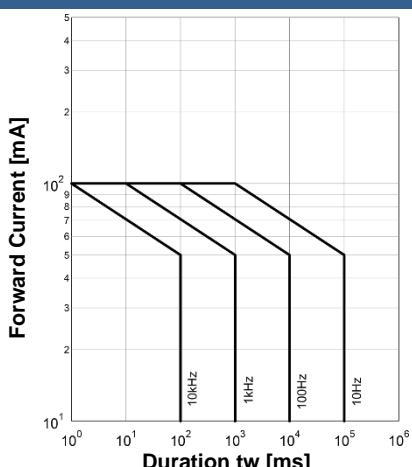
Forward Current vs. Forward Voltage



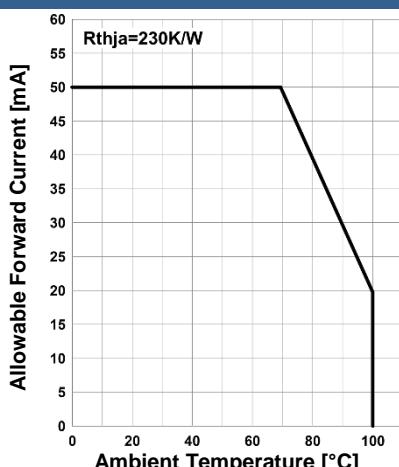
Rel. Radiant Intensity vs. Forward Current



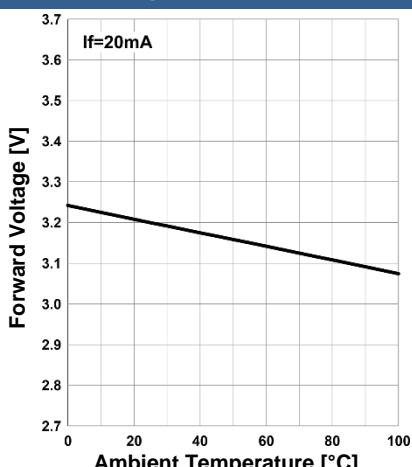
Forward Current vs. Pulse Duration



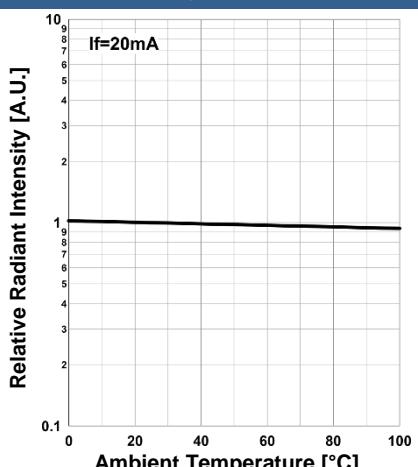
Allowed Forward Current vs. Ambient Temperature

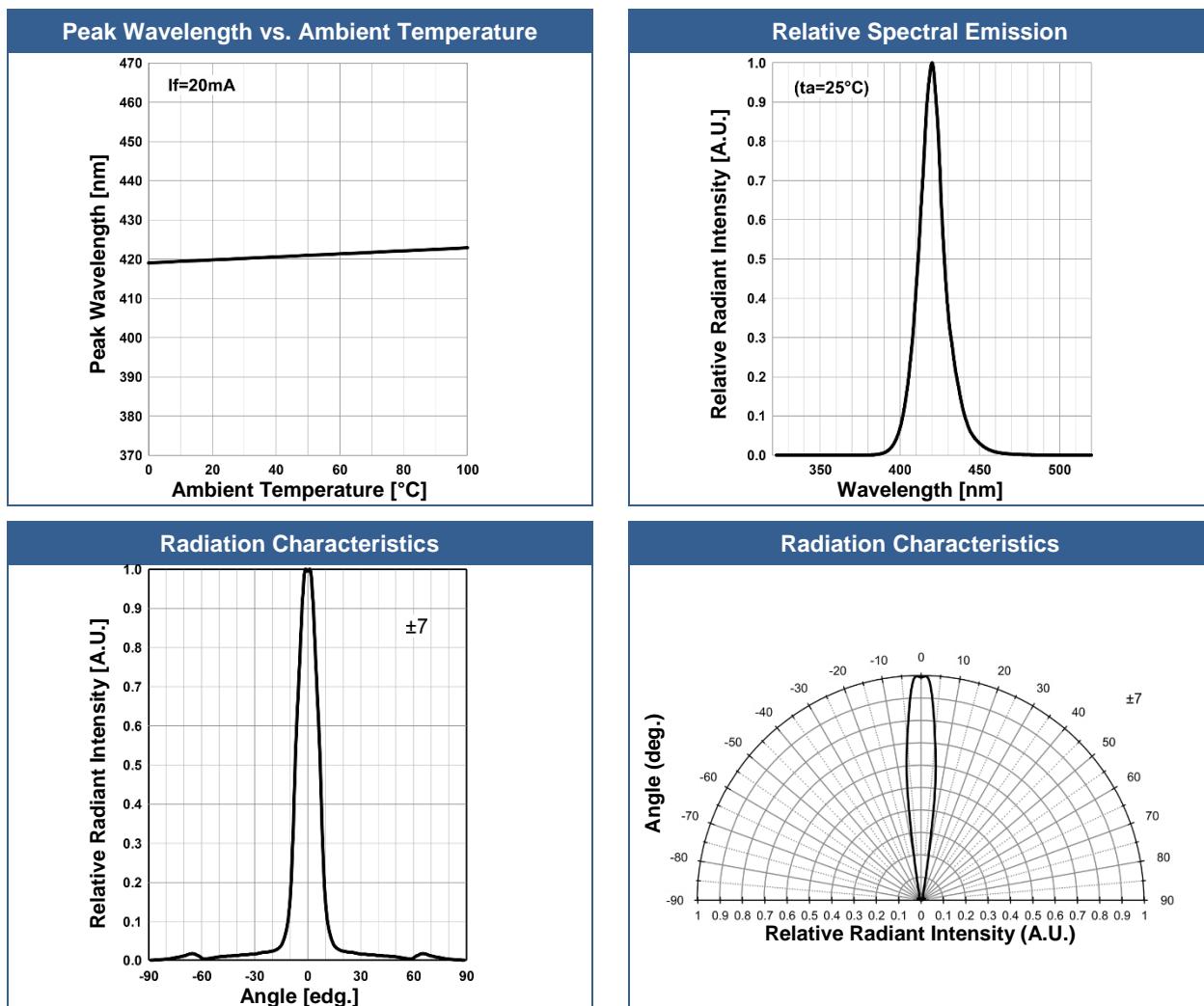


Forward Voltage vs. Ambient Temperature

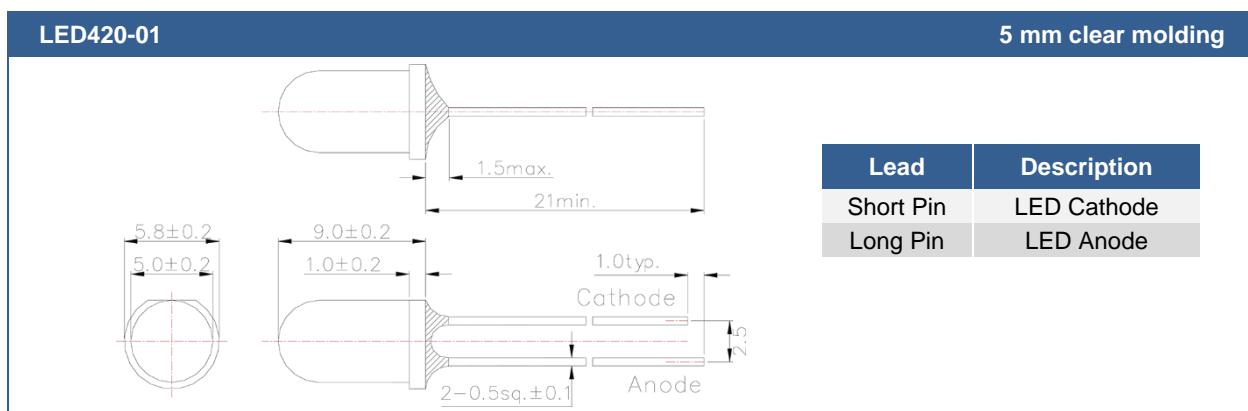


Rel. Radiant Intensity vs. Ambient Temperature





Outline Dimensions



All Dimensions in mm

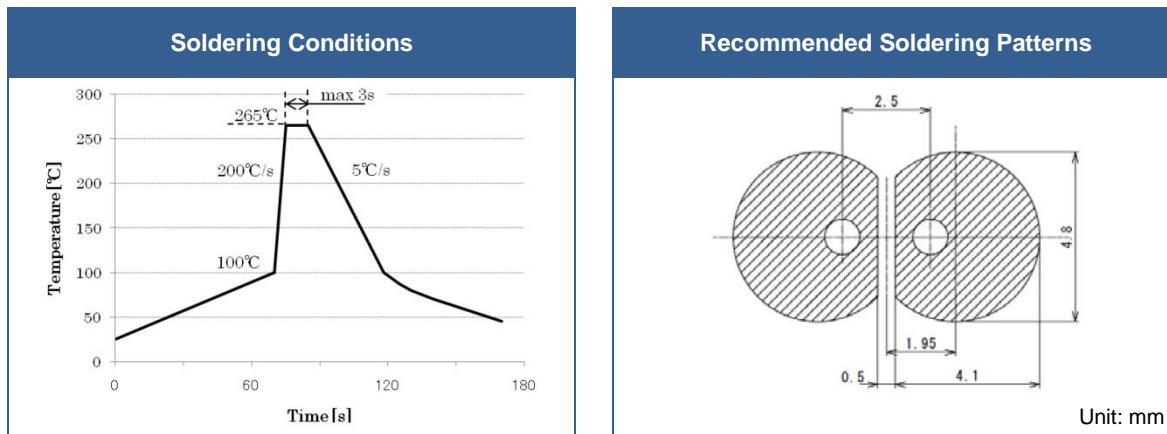


Precautions

Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering
- Do not solder the LED closer than 3 mm from the base of the lead.

Recommended soldering conditions:



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.